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**General Information**

Series	ESD SMD Comm COG
Style	SMD Chip
Description	SMD, MLCC, Temperature Stable, Electro Static Discharge, Class I
Features	Temperature Stable, Low ESR, Class I
RoHS	Yes
Termination	Tin
Marking	No
Typical Component Weight	1.06 mg
Shelf Life	78 Weeks
MSL	1

**Specifications**

Capacitance	1,000 pF
Measurement Condition	1 MHz 1.0Vrms
Tolerance	10%
Voltage DC	25 VDC
ESD Level per AEC-Q200	4,000 V ESD Level
Dielectric Withstanding Voltage	62.5 VDC
Temperature Range	-55/+125°C
Temp. Coefficient	COG
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1MHz 1.0Vrms
Dissipation Factor	0.1% 1 MHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	100 GOhms

**Dimensions**

L	1mm +/-0.05mm
W	0.5mm +/-0.05mm
T	0.5mm +/-0.05mm
S	0.3mm MIN
B	0.3mm +/-0.1mm
Case Code (EIA / mm)	0402 / 1005

**Packaging Specifications**

Packaging	T&R, 330mm, Paper Tape
Packaging Quantity	50000

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